



SOD87

hermetically sealed glass surface mounted package;
ImplotecTM(1) technology; 2 connectors

8 February 2016

Package information

1. Package summary

Terminal position code	E (end)
Package type descriptive code	MELF
Package type industry code	MELF
Package style descriptive code	MELF (metal electrode leadless face)
Package style suffix code	NA (not applicable)
Package body material type	L (glass)
IEC package outline code	100H03
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.3	-	3.5	3.7	mm
ΦD	package diameter		2	-	2.05	2.1	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline

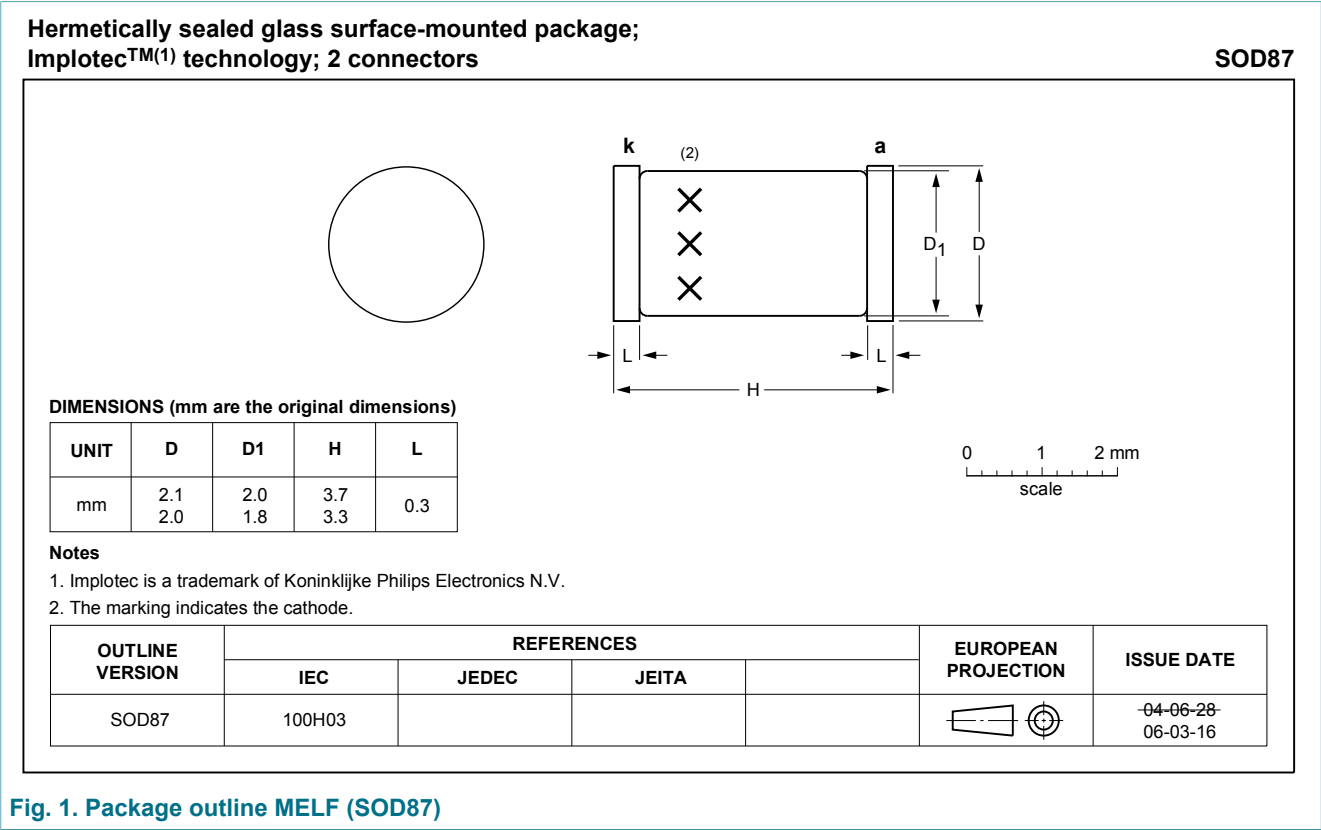
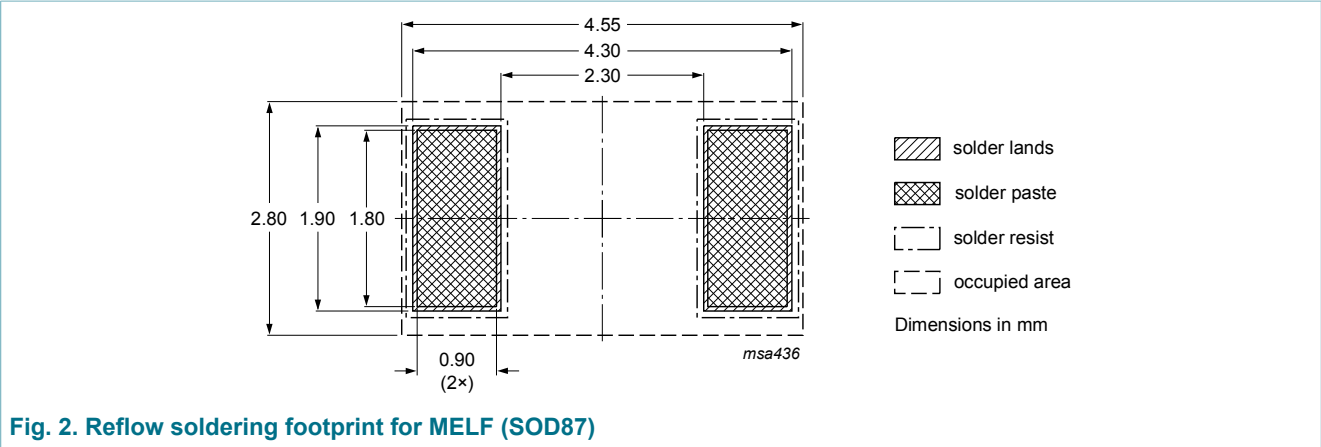


Fig. 1. Package outline MELF (SOD87)

3. Soldering



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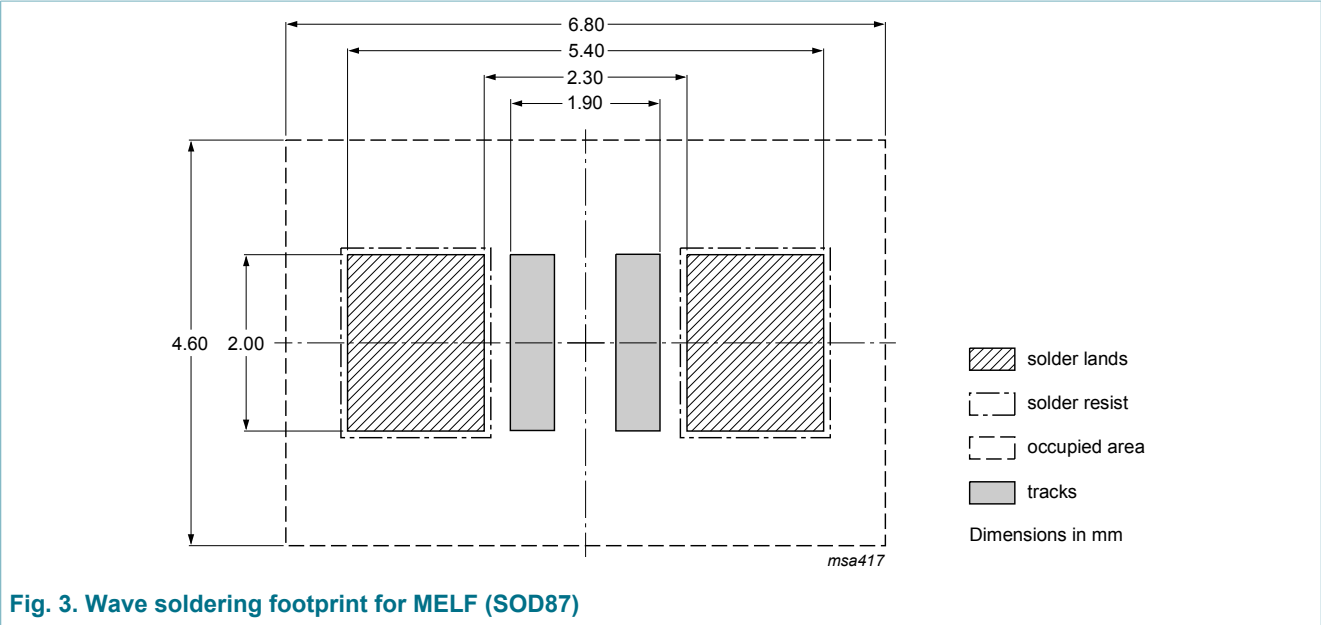


Fig. 3. Wave soldering footprint for MELF (SOD87)

4. Legal information

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Date of release: 8 February 2016